



Material Content Data Sheet



Sales Product Name		ICE3A2565		Issued		29. August 2013		
MA#		MA001054978						
Package		PG-DIP-8-9		Weight*		519.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.491	1.25	1.25	12504	12504
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		103	
	non noble metal	zinc	7440-66-6	0.213	0.04		411	
	non noble metal	iron	7439-89-6	4.266	0.82		8218	
wire	non noble metal	copper	7440-50-8	173.237	33.37	34.24	333697	342429
	noble metal	gold	7440-57-5	0.348	0.07	0.07	670	670
	encapsulation	organic material	carbon black	1333-86-4	1.297	0.25		2499
encapsulation	plastics	epoxy resin	-	37.621	7.25		72466	
	inorganic material	silicondioxide	60676-86-0	285.397	54.98	62.48	549745	624710
leadfinish	non noble metal	tin	7440-31-5	7.496	1.44	1.44	14439	14439
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1543	1543
glue	plastics	epoxy resin	-	0.288	0.06		556	
	noble metal	silver	7440-22-4	1.635	0.31	0.37	3149	3705
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com